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PART NO. KEY POS.		Pos. D	DIM 'P' RECOMMENDED PCB THICKNESS			PLATING OPTION CONTACT AREA TAIL AREA						
78315-	0001		1.85	2.40					0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE			
78315-	0201 CEN (1.5	TER	ده.۱			ER/ 30 MICROINCH ER/ 50 MICROINCH I	MIN. GOLD OVER MIN. NICKEL UNDERPLAT		ICROMETER/15 TO 60 ER/ 50 MICROINCH MIN			
78315-	0011		2.85	2.60		ER/ 30 MICROINCH ER/ 50 MICROINCH I	MIN. GOLD OVER MIN. NICKEL UNDERPLAT		0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE			
						중원 QUALITY	GENERAL TOLERAN	NCLU	N STYLE SCALE		THIRD AN	
					ADDED OPTION EC NO: S2009-03E	A:CCTEH 2009/05 D:CGTAN 2009/05 C:SHLENI 2009/05 DESCRIPTION CONTROL CONTRO	UNLESS SPECIFIED mm 1 4 PLACES ± ± - 3 PLACES ± ± - 2 PLACES ± 0.20 ± - 1 PLACE ± ± - ANGULAR ± 1 DRAFT WHERE APPL MUST REMAIN WITHIN DIMENSION	NCH DRAWN BY CMTEO CHECKED BY CCTEH APPROVED BY SHLENI MATERIAL NO. CABLE SEE SIZE THIS DI	DATE 2008/07/17 DATE 2008/07/30 DATE 2008/08/01 folex	DDR3 DIMM (L 1.00MM PITCH, VERTICAL P/F MOLEX INCOL SD-78315-001	SP, VLP) 240 CKTS , LOWLLCR RPORATED SHEE	